

Claims

[c1] What is claimed is:

1.A wire bonding package comprising:

a housing having a plurality of pins installed;

a circuit board installed inside the housing, the circuit board comprising at least a trace connected to the pins of the housing;

at least a die installed on the circuit board, the die having a plurality of bonding pads installed; and

at least a bonding line connected between the bonding pads of the die and the trace of the circuit board so that the bonding pads of the die are electrically connected to the pins of the housing.

[c2] 2.The wire bonding package of claim 1, wherein the housing comprises a lead frame for accommodating the circuit board.

[c3] 3.The wire bonding package of claim 1 comprising a plurality of die stacked on the circuit board.

[c4] 4.The wire bonding package of claim 1 comprising a plurality of die, at least two of the die adhering to the circuit board.

- [c5] 5.The wire bonding package of claim 1, wherein the housing is a ball grid array (BGA).
- [c6] 6.The wire bonding package of claim 1, wherein the housing is a quad flat package (QFP).
- [c7] 7.The wire bonding package of claim 1, wherein the housing is a dual in-line package (DIP).
- [c8] 8.The wire bonding package of claim 1 further comprising at least a passive component installed on the circuit board.